Ab initio study of magnetic tunnel junctions based on half-metallic and spin-gapless semiconducting Heusler compounds: Reconfigurable diode and inverse TMR effect for magnetic memory and logic applications

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Magnetic tunnel junctions (MTJs) have attracted strong research interest within the last decades due to their potential use as non-volatile memory such as MRAM as well as for magnetic logic applications. Half-metallic magnets (HMMs) have been suggested as ideal electrode materials for MTJs to achieve an extremely large tunnel magnetoresistance (TMR) effect. Despite their high TMR ratios, MTJs based on HMMs do not exhibit current rectification, i.e., a diode effect, which was achieved in a novel MTJ concept [ACS Appl. Electron. Mater. 1, 1552–1559 (2019)] based on HMMs and type-II spin-gapless semiconductors (SGSs). The proposed concept has been recently experimentally demonstrated using Heusler compounds. In the present work, we investigate from first-principles MTJs based on type-II SGS and HMM quaternary Heusler compounds FeVTaAl, FeVTiSi, MnVTiAl, and CoVTiSb. Our ab initio quantum transport calculations based on a nonequilibrium Green's function method have demonstrated that the MTJs under consideration exhibit current rectification with relatively high on/off ratios. We show that, in contrast to conventional semiconductor diodes, the rectification bias voltage window (or breakdown voltage) of the MTJs is limited by the spin gap of the HMM and SGS Heusler compounds, which can be tuned by doping the electrode materials. A unique feature of the present MTJs is that the diode effect can be configured dynamically, i.e., depending on the relative orientation of the magnetization of the electrodes, the MTJ allows the electrical current to pass either in one or the other direction, which leads to an inverse TMR effect. The combination of nonvolatility, reconfigurable diode functionality, tunable rectification voltage window, and high Curie temperature of the electrode materials make the proposed MTJs very promising for room temperature spintronic applications and opens new ways to magnetic memory and logic concepts as well as logic-in-memory computing.

I. INTRODUCTION

The current computing technology is based on the von-Neumann architecture [1], in which the central processing unit and the memory are connected via a shared bus system causing the memory bandwidth bottleneck and high power consumption. It was demonstrated that for many computing tasks, the major amount of energy and time is needed to transfer data between the memory and the CPU, rather than the information processing itself [2, 3]. To tackle the bandwidth bottleneck in today's microprocessors, new information processing concepts such as logic-in-memory computing are receiving substantial interest [4–9]. The logic-in-memory computing architecture requires non-volatile memory elements. Among the emerging non-volatile memory technologies, the magnetoresistive random access memory (MRAM) is the most promising candidate due to its almost infinite endurance. The MRAM combines relatively high access speeds with non-volatility. In particular, spin-transfer torque (STT)-MRAM and spin-orbit torque (SOT)-MRAM emerged as promising candidates to replace the L3- and L2-cache [10, 11] of modern microprocessors.

In conventional magnetic tunnel junctions (MTJs), a non-magnetic insulator of a few nanometer thickness is sandwiched between two ferromagnetic electrodes [12, 13]. Thus, the electronic transport is spin-dependent and mainly determined by quantum tunneling. For this reason, the tunnel magnetoresistance (TMR) ratio and the conductance are very important quantities of MTJs [14– 17]. The resistance of such devices differs in two configurations, when the magnetization of the left and right electrode is parallel oriented and when the orientation is switched to anti-parallel, resulting in the TMR effect. When no bias voltage is applied, the TMR ratio is defined as TMR = $(G_{\uparrow\uparrow} - G_{\uparrow\downarrow})/(G_{\uparrow\downarrow} + G_{\uparrow\uparrow})$, where $G_{\uparrow\uparrow}$ ($G_{\uparrow\downarrow}$) denotes the conductance in the parallel (antiparallel) configuration of the electrodes. For finite biases, the TMR expression becomes TMR = $(I_{\uparrow\uparrow} - I_{\uparrow\downarrow}) / (I_{\uparrow\downarrow} +$ $I_{\uparrow\uparrow}$), where $I_{\uparrow\uparrow}$ $(I_{\uparrow\downarrow})$ is the tunnel current through the device in the parallel (anti-parallel) orientation of the magnetization of the electrodes. It is worth noting that the tunnel barrier material, as well as the thickness of the tunnel barrier, and the applied bias voltage can influence the TMR effect [13, 18, 19]. Another factor that can affect the sign and the value of the TMR ratio is a structural asymmetry in the junctions. Heiliger *et al.* proposed that independent of the applied bias voltage, in asymmetric junctions the value of $I_{\uparrow\downarrow}$ exceeds the amount of $I_{\uparrow\uparrow}$ and, as a consequence, leads to a negative TMR ratio [20, 21]. The dependency of the TMR ratio on the applied bias voltage for both, the normal and the inverse TMR effect, is schematically illustrated in Fig. 1 (a).

MTJs played a significant role in spintronics develop-

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FIG. 1. (a) Top: Schematic representation of the magnetic tunnel junction based on a half-metallic magnet and a spin gapless semiconductor. Bottom: Dependency of the TMR effect on the bias voltage in MTJs. The inverse (i-)TMR effect is illustrated by a blue line while the normal (n-)TMR effect is represented by a red dashed line. (b) and (c) The same as (a) for the parallel and anti-parallel orientation of the magnetization directions of the electrodes as well as the corresponding current-voltage (I-V) characteristics. The white arrows indicate the magnetization direction of the electrodes.

ment as they are suitable for several applications ranging from read-head sensors to non-volatile memory devices such as STT-MRAM and SOT-MRAM and from non-volatile logic concepts to logic-in-memory computing [22–24]. Magnetic logic promises non-volatile, lowpower computing and up to now, several different approaches have been proposed such as the quantum cellular automata [25, 26], domain-wall logic [27, 28], MTJ logic [29–31], etc. The latter is of particular interest because it opens the way to logic-in-memory computing, i.e., storing and processing the data within the same chip and thus providing an opportunity to explore novel computing architectures beyond the classical von-Neumann architecture [32, 33]. MTJ-based magnetic logic proposals can be divided into three categories: i) external fielddriven MTJ logic, ii) spin Hall effect driven MTJ logic, and iii) logic based on magnetic tunnel diodes and magnetic tunnel transistors.

In the first category, the logic gates are built from MTJs, which are arranged in a bridge-type configuration and the logic inputs are provided by external wires. which creates a magnetic field that switches the magnetization direction of one electrode in MTJ. In this way, all logic gates can be realized with few MTJs [29, 30, 34]. The utilization of an inverse TMR effect can even further reduce the number of MTJs in logic gates [31, 35]. However, the drawback of this approach is that it is not scalable due to input wires and their routing near the MTJs. In the second category, the logic gates are based on a novel four-terminal spin Hall effect driven MTJ with fully electrically-separated write/read paths [36–38]. These four-terminal MTJ devices can overcome the challenges of operation gain and direct cascading in current spintronic logic circuits. Moreover, simulations have indicated that correct logic fan-out operation can be achieved with voltage below 150 mV, which is promising for low power computing [38]. Note that in both approaches the logic operation gain (i.e., output voltage margin) depends mainly on the TMR ratio of the MTJs. While in the third category, a MTJ possesses, in addition to the TMR effect (memory), a current rectification (diode effect) functionality. Such MTJs also constitute the basic building blocks of the three-terminal magnetic tunnel transistors for logic applications. The TMR effect and current rectification have been observed for single barrier asymmetric MTJs as well as for double barrier MTJs with tunnel barriers of different transparency [39– 42]. Although in initial studies of magnetic tunnel transistors low magnetocurrent ratios and transfer rates α are reported [43–47], in recent experiments of fully epitaxial magnetic tunnel transistors a large magnetocurrent ratio and transfer rate α is detected [48]. Besides being the basic building blocks of the three-terminal magnetic tunnel transistors, the MTJs possessing the diode effect is of particular interest for high-density 3D cross-point STT-MRAM applications as it eliminates the need for an additional selection device [42], i.e., a MOSFET transistor or a p-n diode [49–51].

In contrast to MTJ-based logic proposals, in the first and second category as well as other concepts like spinorbit torque logic [52] not mentioned above (for a detailed discussion the reader is referred to Refs. 53 and 54, which report a benchmarking of beyond-CMOS devices including various spintronic logic concepts), magnetic tunnel diodes and transistors can operate extremely high frequencies, i.e., in THz regime, making them ideal candidates for high speed electronic and spintronic applications. However, despite THz operation frequencies, conventional magnetic tunnel diodes and transistors come with fundamental issues such as low on/off current ratios and less asymmetric current-voltage characteristics in diodes and base-collector leakage currents in transistors, which might lead to high power dissipation. In Ref. 55, we have proposed a magnetic tunnel diode and transistor concept, which overcomes the limitations of conventional magnetic tunnel devices and provides additional unique functionalities like reconfigurability, which was recently experimentally demonstrated [56]. The concept is based on spin-gapless semiconductors (SGSs) [57] and half-metallic magnets (HMMs) [58]. The two-terminal magnetic tunnel diode (or MTJ) is comprised of a SGS electrode and a HMM electrode separated by a thin insulating tunnel barrier. A schematic representation of the structure of the reconfigurable magnetic tunnel diode is shown in Fig. 1 (b) and 1 (c). Depending on the relative orientation of the magnetization of the electrodes the MTJ allows the electrical current to pass either in one or the other direction.

The aim of the present paper is a computational design of MTJs based on HMM and SGS quaternary Heusler compounds for room temperature device applications. Heusler compounds offer a unique platform to realize MTJs as these materials possess very high Curie temperatures (above room temperature) as well as HMM and SGS behavior within the same family [59–61]. To this end, the selection of the HMM and SGS electrode materials from the quaternary Heusler family for the design of MTJs is based on our recent study in Ref. 61. We stick to SGS FeVTaAl and FeVTiSi compounds due to their large energy gaps in opposite spin channels around the Fermi level [61], MgO as tunnel barrier due to the lattice matching, and for the HMMs, although we have a large variety of choice, we choose MnVTaAl and CoFeVSb since both materials exhibit nearly symmetric spin gaps above and below E_F and possess similar lattice constants to MgO. Ab initio quantum transport calculations based on the non-equilibrium Green's function (NEGF) method have demonstrated that the MTJs based on HMM and SGS Heusler compounds exhibit, in addition to inverse TMR effect, current rectification, i.e, diode effect, which can be dynamically configured. We show that in contrast to semiconductor diodes (p-n diode or Schottky diode), the rectification voltage window (or breakdown voltage) of these MTJs is limited by the spin gap of HMM and SGS Heusler compounds, which can be tuned by doping electrode materials. The calculated zero temperature on/off current ratios vary between $10^2 - 10^7$, being lowest for the FeVTiSi/MgO/CoFeVSb MTJ, which can be attributed to the overlap of the conduction and valence bands of opposite spin channels around the Fermi level. The combination of non-volatility and dynamically reconfigurable diode effect as well as the very high Curie temperature of quaternary Heusler compounds make the proposed MTJs very promising for room temperature spintronic memory and logic applications. The rest of the paper is organized as follows: In Section II, we discuss the *I-V* characteristics of the MTJ concept by using the spin-dependent energy-band diagrams. In Section III, we present the computational details of our study. Our computational results are presented and discussed in Section IV, and finally, in Section V, we give our summary and outlook.

II. HMM/I/SGS MAGNETIC TUNNEL JUNCTIONS

In Fig. 1 (b) and 1 (c), we schematically show a MTJ based on a HMM and a SGS in the parallel and antiparallel configuration of the electrodes, respectively, together with the corresponding I-V curves. HMMs have been used as electrode materials for MTJs to achieve extremely large TMR effects. Despite their large TMR ratios, the MTJs based on HMMs do not present current rectification, i.e., a diode effect. In Ref. 55, it was proposed that replacing one of the HMM electrodes with a SGS material in a MTJ gives rise to additional functionalities, i.e., current rectification, inverse TMR effect, and reconfigurability of the MTJ. Such a MTJ is then called a reconfigurable magnetic tunnel diode (MTD). Besides the HMM, the SGS material is the key component of the MTD. SGSs have been proposed by Wang in 2008 as a theoretical concept [57]. By employing first-principles



FIG. 2. Schematic representation of the density of states for (a) a type-II spin-gapless semiconductor, (b) a half-metallic magnet, and (c) a type-I spin-gapless semiconductor.

calculations Wang demonstrated that doping PbPdO₂ with Co atoms results in a new class of materials: the SGSs [57, 62]. Since then, different classes of materials have been predicted to present SGS behavior of various types, i.e., from type-I to type-IV SGSs [57, 59–61, 63– 65] and some of the predicted SGSs have been experimentally realized [66]. Since type-II SGSs are the key component of the reconfigurable MTD, in Fig. 2 we present the schematic density of states (DOS) of a type-II SGS together with a conventional HMM as well as a type-I SGS. which can be also used as a replacement of the HMM in a MTJ. As seen in Fig. 2 (a) the type-II SGS possesses a unique electronic band structure, i.e., it presents a finite gap below and above the Fermi level E_F in different spin channels while the valence- and conduction-bands of different spin channels touch at E_F . On the other hand, in HMMs, the majority-spin channel behaves like in normal metals, but the minority-spin channel exhibits a gap around the Fermi level like in a semiconductor or insulator. The DOS of type-I SGSs is similar to HMMs [see Fig. 2(b) and 2(c)]. The minority-spin channel looks the same while in the majority-spin channel a zero-width gap appears at the Fermi level since the conduction- and valence-band edges touch at E_F .

The operation principle of the reconfigurable MTD is extensively discussed in Ref. 55 and hence here we present a short overview of the concept by using the spin-resolved energy-band diagram shown in Fig. 3. The spin-resolved energy-band diagram is based on the schematic DOSs provided in Fig. 2(a) and 2(b), i.e., the type-II SGS material possesses a gap in the minority-spin (majorityspin) channel below (above) the Fermi level while the HMM exhibits a gap in the minority-spin channel around the Fermi energy. We further assume that the type-II SGS electrode, the tunnel barrier, and the half-metallic material have the same work function and equal Fermi levels and therefore we do not consider charge transfer at the interfaces. However, real materials, as it will be discussed in Section IV, possess different work functions and so there occurs charge transfer between one material and the other at the interface, which might cause a band bending in the SGS electrode. Moreover, due to interactions at the interface, the junction materials might not conserve the SGS or HMM characteristics close to the interface and thus the band diagram will not be as sharp as presented in Fig. 3.



FIG. 3. Schematic representation of the spin-resolved energy-band diagram for the SGS/I/HMM MTJ for parallel (P) orientation of the magnetization directions of the electrodes (a) for zero bias, (b) under forward bias, and (c) under reverse bias. The electrons (holes) and the Fermi energy are denoted by red (white) spheres and a dashed line, respectively, and the tunneling process is illustrated by partly shaded red arrows. (d), (e), and (f) represent the same as (a), (b), and (c) for the anti-parallel (AP) orientation of the magnetization directions of the electrodes [see Figure 1 (b) and 1 (c)].

The *I-V* characteristics of the SGS/MgO/HMM junction illustrated in Fig. 1(b) and 1(c) can be qualitatively explained by Bardeen's approach for tunneling [67, 68]. For a simple tunnel barrier, the tunnel current I(V) is given by the expression $I(V) \sim$ $\sum_{\sigma} \int_{-\infty}^{+\infty} \rho_{\rm HMM}^{\sigma}(E+eV) \rho_{\rm SGS}^{\sigma}(E) |T(V)|^2 f(E) \left[1-f(E+eV)\right] dE, \text{ where } \rho_{\rm SGS}^{\sigma}(E) \text{ and } \rho_{\rm HMM}^{\sigma}(E+eV) \text{ denote the}$ DOS of the SGS and HMM electrodes with spin σ and f(E) being the Fermi distribution function. T(V) is the transmission probability, which is proportional to $e^{-d\sqrt{\phi-V}}$, where d is the thickness of the tunnel barrier and ϕ is the barrier height. As shown in Fig. 3 (b), when the magnetization directions of the electrodes are aligned parallel and a positive bias voltage (forward bias) is applied to the SGS electrode, electrons in the occupied majority-spin valence band of the HMM electrode cannot tunnel through the insulating barrier into the SGS electrode because there are no available states above the Fermi energy in the majority-spin channel of the SGS electrode unless a certain bias voltage is reached. For minority-spin electrons, the HMM electrode behaves like an insulator and thus no electron transport takes place. For a negative bias voltage (reverse bias), electrons in the majority-spin channel in the SGS material can tunnel into the unoccupied states of the HMM as shown in Fig. 3(c). In the minority-spin channel, neither in the SGS electrode nor in the HMM electrode states are available that can contribute to a current. Thus, the tunneling current through the MTJ is 100% spin-polarized. A similar discussion holds for the anti-parallel orientation

of the magnetization direction of the SGS and HMM electrodes, for which the corresponding energy-band diagram is presented in Figs. 3 (d)-(f). Note that in the schematic representation of the I-V characteristics of the MTJ [see Fig. 1 (b) and 1 (c)], we use the standard definition of current for semiconductor devices, i.e., the current direction is opposite to the electron motion direction, while in Ref. 55, the same direction is taken for the current and electron motion. This is why the I-V characteristics are different in Ref. 55.

The presence of the reconfigurable diode effect in MTJs based on SGSs and HMMs leads to an inverse TMR effect rather than a normal TMR effect as in most of the conventional MTJs. The voltage dependence of the TMR presented in Fig. 1 (a) can be explained on the basis of the *I-V* characteristics discussed above. For a positive (forward) bias voltage, $I_{\uparrow\downarrow}$ will take a finite value while $I_{\uparrow\uparrow}$ is equal to zero. While for a negative (reverse) bias voltage, the situation is exactly the opposite. Thus, for forward bias, the TMR ratio will take the value -100%in a bias voltage window, which is set by the bandgap of the SGS and HMM electrodes. Similarly, under a reverse bias, the TMR ratio will be normalized to +100%. Note that we use here a different definition of the TMR ratio compared to the Jullière model [69].

Up to now, the discussion of the I-V curves and voltage dependence of the TMR effect in SGS/I/HHM MTJs was based on the schematic energy-band diagram at zero temperature and perfect SGS behavior of the electrode material. However, at finite temperatures, thermally ex-

TABLE I. Material composition of the considered MTJs, lattice constants a_0 , c/a ratio, sublattice and total magnetic moments, work function (Φ), Curie temperatures T_C of the cubic phase, and the electronic ground state. All T_C values are taken from Ref. 61.

SGS/MgO/HMM junction	MgO-interface	Compound	a_0	c/a	m_X	$\mathbf{m}_{X'}$	m_Y	$\mathrm{m}_{\mathrm{total}}$	Φ	T_C	Ground state
			(Å)		(μ_B)	(μ_B)	(μ_B)	(μ_B)	(eV)	(K)	
FeVTaAl/MgO/MnVTiAl	FeV-MnV	FeVTaAl	6.10	1.00	0.85	2.38	-0.19	3.00	3.75	681	SGS
		MgO	6.10	0.98	-	-	-	-	4.53	-	Ι
		MnVTiAl	6.10	1.01	-2.42	2.61	0.86	1.00	3.59	963	HMM
FeVTiSi/MgO/CoFeVSb	FeV-CoFe	FeVTiSi	5.91	1.00	0.57	2.33	0.10	3.00	3.52	464	\mathbf{SGS}
		MgO	5.91	1.04	-	-	-	-	4.55	-	Ι
		CoFeVSb	5.91	1.12	1.08	1.20	0.78	3.00	4.10	308	HMM

cited electrons (non-spin-flip processes) can be transmitted from one electrode to the other in the off-state and thus cause a leakage current [see Figs. 3 (b) and 3 (f)]. This reduces the on/off and TMR ratios. Nevertheless, such processes can be significantly reduced by increasing the bandgap of the SGS and HMM materials as the Fermi-Dirac distribution function decays exponentially with increasing energy. Besides thermally excited non-spin-flip electrons, spin-flip processes stemming from spin-orbit coupling and electron-magnon interaction can also reduce the on/off ratio as well as the TMR effect [70– 72].

III. COMPUTATIONAL DETAILS

Our ab initio study of the SGS/MgO/HMM MTJs is based on spin-polarized density functional theory (DFT) using the QUANTUMATK software package (version S-2021.06) [73, 74]. We used linear combinations of atomic orbitals (LCAO) as basis-set together with norm-conserving PseudoDojo pseudopotentials [75] with the Perdew-Burke-Ernzerhof (PBE) parametrization of the exchange-correlation functional [76]. For the determination of the ground-state properties, we use a $15 \times 15 \times 15$ Monkhorst-Pack **k**-point grid and as density mesh cutoff for the separation of core and valence electrons 145 Hartree. Since the PBE-GGA is well-known to underestimate band gaps [77–79], we use the DFT-1/2 method [80, 81] as implemented in the QUANTUMATK package to correct the bandgap in the calculations of the transmission spectra. The changes in the SGS and HMM band structure by applying the DFT-1/2 method are negligible. For the structural optimization, all forces converge to at least $0.01 \,\mathrm{eV/\AA}$ and selfconsistency was achieved when the energies between two steps of the SCF cycle differ less than 10^{-4} eV. For the transport calculations, we employ the non-equilibrium Green's function (NEGF) approach combined with the DFT method using an $11 \times 11 \times 115$ k-point mesh. To calculate the *I-V* characteristics, QUANTUMATK applies the Landauer-Büttiker approach [82], where $I(V) = e/h \sum_{\sigma} \int T^{\sigma}(E, V) \left[f_L(E, V) - f_R(E, V) \right] dE$, where $f_L(E, V)$ and $f_R(E, V)$ represent the Fermi-Dirac distribution of the left and right electrode, respectively. Furthermore, the transmission coefficient $T^{\sigma}(E, V)$ depends on the spin σ of the electrons, the applied bias voltage V, and the energy E. For the calculation of $T^{\sigma}(E, V)$, we chose a dense 100 × 100 k-mesh. Moreover, the self-consistent I-V calculations are compared with a zero-bias linear response approach.

IV. RESULTS AND DISCUSSION

In Section II, we qualitatively discussed the *I-V* characteristics of the MTJs based on SGSs and HMMs using the spin-dependent energy-band diagram and a simple tunnel barrier model. However, quantum tunneling is a very sophisticated process in real materials as it depends on the symmetry of the wave functions in the electrodes, their decay rate, and their matching at the interface. The decay rate is determined by the thickness and barrier height as well as the complex energy bands of the insulating material [83, 84]. Therefore, fully ab initio quantum transport calculations are needed to determine the *I-V* characteristics of the MTJs based on SGSs and HMMs. We choose FeVTaAl and FeVTiSi guaternary Heusler compounds as SGS electrode together with MnVTiAl and CoFeVSb as HMM electrode and construct two different types of MTJs. All four electrode materials possess Curie temperatures above room temperature as presented in Table I. To construct the MTJs, we take the type-II SGS electrode material in the cubic structure and relax the tunnel barrier MgO as well as the HMM electrode material with respect to the inplane lattice parameter of the first electrode. For this reason, we include the c/a ratios for the HMM electrodes and MgO, respectively, which take the tetragonal structure in Table I. The atomic structure of one MTJ is illustrated in Fig. 4(a). The left electrode FeVTaAl is a SGS, the right electrode MnVTiAl is a HMM, and MgO acts as a tunnel barrier. The FeVTaAl (MnVTiAl) has two types of interface terminations with MgO: FeV and TaAl (MnV and TiAl). Our total energy calculations have shown that the FeV-MgO (MnV-MgO) ter-



FIG. 4. (a) The atomic structure of the FeVTaAl/MgO/MnVTiAl tunnel junction. The system is periodic in xy-plane orthogonal to the z-axis, which is the transport direction. The red arrows mark the direction and the size of the magnetic moments within the scattering region. The small induced magnetic moments are overlayed by the atomic radii. The black dashed boxes illustrate the interface. (b) The calculated spin-resolved bulk band structure along the device stack direction, [001], for FeVTaAl (left panel) and MnVTiAl (right panel). The dashed black line denotes the Fermi level which is set to zero.

mination possesses lower energy. Similarly, as for the second MTJ FeVTiSi/MgO/CoFeVSb (see Table I), the FeV-MgO (CoFe-MgO) termination has lower energy.

For both MTJs, the thickness of the MgO tunnel barrier varies between three and six monolayers (0.6-1.4 nm)and the SGS and HMM electrodes are constructed by repeating the minimal tetragonal unit cell five times along the [001] direction. Depending on the number of MgO layers, the length of the device (screening region) lies between 60 Å and 66 Å. The device is periodic in the xyplane and the z-direction is the transport direction. We adjusted the alignment of the magnetic moments to the z-axis. The direction and magnitude of the atomic magnetic moments of the electrode materials in the MTJ are represented by the red arrows and their size in Fig. 4(a). At both interfaces, the magnetic moments deviate from their bulk values (see Table I). At the FeVTaAl-MgO interface, the largest difference is obtained for the Fe atom whose magnetic moment increases from $0.85 \,\mu_B$ to $1.82 \mu_B$ while the moment of the Ta atom decreases from $\sim 0.2 \,\mu_B$ to $-0.4 \,\mu_B$. The changes at the remaining atoms are negligible. Similar behavior is observed for the MnVTiAl-MgO interface, where the largest deviation occurs in the magnetic moment of the Mn atom, whose value decreases from $-2.42 \,\mu_B$ to $-3.30 \,\mu_B$ while the magnetic moments of the other atoms remain more or less unchanged.

Next, we will discuss the electronic properties of the FeVTaAl/MgO/MnVTiAl junction at zero bias, i.e., in

equilibrium. Thus, we present the bulk band structure along the transport direction of both junction materials in Fig. 4 (b). The MnVTiAl compound exhibits a nearly symmetric bandgap of 330 meV above and 310 meV below the Fermi level in the minority-spin channel, while FeVTaAl exhibits a type-II SGS behavior. Note that in the chosen direction, the SGS properties are not well displayed, and thus for a full band structure the reader is referred to Refs. 60 and 61. As we discussed above, the strong variation of the magnetic moments at the interface implies that the HMM and SGS properties are also lost. The loss of the HMM and SGS properties stems from two factors: i) electronic structure, i.e., the Fe and V (Mn and V) atoms at the interface possess different local atomic environments, and thus non-bonding states can emerge close to the Fermi level. Such states significantly reduce the spin-polarization at the interface [85, 86]. ii) Charge transfer across the tunnel junction due to the work function difference of the electrodes (see Table I). Since MnVTiAl exhibits the lower work function, electrons flow from the majority-spin (minority-spin) channel of MnVTiAl to the majority-spin (minority-spin) channel of FeVTaAl for parallel (anti-parallel) alignment of the magnetization directions of the electrodes. When this charge redistribution reaches equilibrium, MnVTiAl is positively charged near the interface region, whereas FeVTaAl is negatively charged and, as a result, an electric dipole is induced, which affects the electronic as well as the magnetic properties of both electrode materials



FIG. 5. (a) Projected device density of states (DDOS) for the majority (left panels) and minority (right panels) spin channel of the FeVTaAl/MgO/MnVTiAl junction for parallel orientation of the magnetization directions of the electrodes under an applied bias of +0.3 V and -0.3 V (the corresponding atomic structure is presented in 4 (a)). In the middle panels we show the calculated transmission spectrum for both spin channels. The dashed lines display the Fermi level of the left and right electrodes while the vertical yellow dashed lines denote the interfaces between the electrodes and MgO. The MgO tunnel barrier thickness is taken to be 1.1 nm, i.e., five monolayers. (b) The same as (a) for anti-parallel orientation of the magnetization directions of the electrodes. The majority and minority spin-channel are illustrated with respect to the magnetic orientation of the left electrode.

around the interface region. The loss of HMM and SGS properties at the interface region can be seen in the device density of states (DDOS) presented in Fig. 5 (see also Fig. 2 in the supplemental material [87]).

The I-V characteristics of the MTJs under consideration are calculated by using two different approaches: i) finite-bias NEGF method and ii) a linear response approach. The latter is computationally much cheaper, while, however, significant differences may appear in the calculated I-V curves when compared to the selfconsistent NEGF calculations as will be discussed below. In the middle panels of Fig. 5 (a) and 5 (b), we present the calculated transmission spectrum for the FeVTaAl/MgO/MnVTiAl MTJ for the applied bias voltage of +0.3 V and -0.3 V for the parallel and anti-parallel configuration of the magnetization direction of the elec-



FIG. 6. (a) The current-voltage characteristics for the FeVTaAl/MgO/MnVTiAl (left panel) and FeVTiSi/MgO/CoFeVSb junction (right panel) for five monolayers of MgO barrier thickness in the parallel configuration. The *I-V* curves are calculated using both SCF and LR methods. (b) The same as (a) for the anti-parallel alignment of the magnetization directions of the electrodes. (c) and (d) illustrate the origin of the leakage current under forward and reverse bias for parallel and anti-parallel orientation of the magnetization direction of the electrodes, respectively.

trodes, respectively. The transmission spectrum and consequently the *I-V* curves of the FeVTaAl/MgO/MnVTiAl MTJ displayed in Fig. 6 can be explained on the basis of the DDOS [Fig. 5(a) and 5(b)]. For parallel orientation of the magnetization directions of the electrodes. under forward bias (V = +0.3 V), the transmission coefficient for majority-spin electrons is zero due to the gap in the type-II SGS material above the Fermi level. Since MnVTiAl exhibits a gap in the minority-spin channel around the Fermi energy, the transmission coefficient is also zero for minority-spin electrons and thus the MTJ is in off-state, i.e., no current flows through it under forward bias. Under reverse bias (V = -0.3 V), majorityspin electrons of occupied states in the SGS electrode FeVTaAl can tunnel into unoccupied states of the HMM electrode MnVTiAl through the MgO tunneling barrier and, as a consequence, the transmission coefficient takes a finite value. In the minority-spin channel, FeVTaAl possesses a gap below E_F and MnVTiAl below and above the Fermi level, and hence, in both materials, no states are available which could contribute to a current within the applied voltage window. Thus, the on-current of the MTJ in parallel configuration is 100% spin-polarized.

Switching the magnetization direction of the electrodes from the parallel to the anti-parallel configuration results in switching the I-V characteristics of the MTJ (see Fig. 1 (b) and 1 (c)), i.e, the MTJ is in on-state under forward bias, while it is in off-state under reverse bias. In this case, the HMM electrode MnVTiAl possesses a gap in the majority-spin channel and thus this channel does not contribute to the current. However, in the minorityspin channel, electrons from the occupied states above the Fermi energy in MnVTiAl can tunnel through the MgO tunnel barrier into unoccupied states in FeVTaAl, and thus the transmission coefficient takes a finite value under forward bias, which leads again to a 100 % spinpolarization of the current. While for a reverse bias, no current flows through the MTJ since in the majorityspin channel the HMM electrode MnVTiAl possesses a gap around the Fermi energy, while in the minority-spin channel the SGS electrode FeVTaAl presents a gap below E_F , and hence for both spin channels the transmission coefficient is zero.

In Fig. 6 (a) and 6 (b), we present the I-V characteristics of both MTJs within the finite-bias NEGF method, which will be called self-consistent field (SCF) and the linear response approach (LR) for a MgO thickness of five monolayers (1.1 nm). As seen for the parallel orientation of the magnetization direction of the electrodes, both MTJs are in off-state under forward bias and in onstate under reverse bias. However, this might be seen as contradicting to the conventional p-n diodes, in which the diode is in on-state under forward bias. In our case this is a matter of the construction of the MTJ, i.e., by exchanging the electrode materials, one obtains the I-Vcharacteristics of conventional diodes. In the SCF calculations, we obtain a monotonic increase of the current I with bias voltage V for both MTJs with zero turnon voltages V_T for both FeVTaAl/MgO/MnVTiAl and FeVTiSi/MgO/CoFeVSb junctions in the parallel configuration, respectively. Switching the magnetization direction of the HMM electrode from parallel to anti-parallel results in switching the I-V characteristics of the MTJs as shown in Fig. 6(b). Both MTJs are now in onstate under forward bias, while they are in off-state under reverse bias. In contrast to the parallel alignment of the magnetization directions, in this case, the turnon voltage V_T for the FeVTiSi/MgO/CoFeVSb is large, i.e., 0.25 V, which can be understood on the basis of the DDOS presented in supplemental material [87]. The large work function difference of the electrode materials (FeVTiSi and CoFeVSb) gives rise to a band bending in the energy-band diagram of this MTJ and as a consequence one obtains an effectively thick tunnel barrier for small bias voltages, which leads to a large turn on voltage under forward bias. Furthermore, the on-state currents for parallel and ati-parallel configurations of the same MTJ is also quite different. For instance, in the FeVTaAl/MgO/MnVTiAl junction for the parallel configuration the on-state current is one order of magnitude larger than the corresponding current in the anti-parallel configuration, while in the FeVTiSi/MgO/CoFeVSb junction the situation is different, here the on-state current is by a factor of two smaller in the parallel configuration. For comparison, the I-V curves obtained from the linear-response approach have been included in Fig. 6(a) and 6(b). As seen, qualitatively the linear response current follows the SCF results with some differences such as the turn-on voltage in the case of the FeVTaAl/Mgo/MnVTiAl junction in the parallel configuration and the overestimated leakage current in the case of the FeVTiSi/MgO/CoFeVSb junction also for the parallel configuration. We do not expect a quantitative agreement between these approaches because for the linear response method one assumes a bias-independent transmission spectrum and thus this method is not capable of an accurate description of the *I-V* characteristics. The zero-bias transmission spectrum for the linear response calculations of both MTJs can be found in the supplemental material [87].

We now would like to comment on the off-state leakage currents of both MTJs. In principle, at zero temperature, one would obtain a zero off-state current for a perfect SGS electrode. However, in our MTJs both SGS electrodes, FeVTaAl and FeVTiSi, possess a sizeable band overlap between the valence and conduction bands of opposite spin channels around E_F as schematically illustrated in Figs. 6 (c) and 6 (d) (see also the supplemental material of Ref. 61 for the DOS). For parallel (anti-parallel) aligned magnetization directions of the electrodes, band overlaps allow majority-spin (minority-spin) electrons to tunnel from the occupied states of the HMM (type-II SGS) electrode through the insulating region into unoccupied states of the type-II SGS (HMM) material. Since FeVTiSi possesses an overlap of 150 meV whereas the overlap in FeVTaAl amounts to just 60 meV, a larger leakage current arises in the FeVTiSi/MgO/CoFeVSb junction. At zero temperature, the obtained on/off current ratios of both MTJs at $\pm 0.3 V$ vary between 10^2 and 10^7 .

In contrast to conventional semiconductor diodes (p-n diode, Schottky diode, Zener diode), in which the rectification bias voltage window (or reverse bias breakdown voltage of the diode) varies between 3-200 V, in the present MTJs, this voltage window is limited by the spin gap of the HMM and SGS Heusler compounds. In analogy to conventional semiconductor diodes, we can express the breakdown voltage for the parallel and anti-parallel configurations as $V_B^{\rm P} = min\{(\mathrm{SG}_{\mathrm{SGS}}, E_F^{\rm A}), (\mathrm{SG}_{\mathrm{HMM}}, E_F^{\rm B})\}$ and $V_B^{\rm AP} = min[(\mathrm{SG}_{\mathrm{SGS}}, E_F^{\rm B}), (\mathrm{SG}_{\mathrm{HMM}}, E_F^{\rm A})]$, where $(\mathrm{SG}_{\mathrm{SGS}}, E_F^{\rm A})$ and (SG_{HMM}, E_F^B) stand for the spin gap of the SGS and HMM electrodes above and below the Fermi energy, respectively. Using the spin gap values of the SGSs and HMMs from Ref. 61, one gets breakdown voltages $V_B^{\rm P}~(V_B^{\rm AP})$ of 0.31 V and -0.34 V (0.33 V and -0.30 V) for the parallel (anti-parallel) configurations of the FeVTaAl/MgO/MnVTiAl and FeVTiSi/MgO/CoFeVSb MTJ, respectively. Since the estimation of the breakdown voltage is based on the DOS picture of the materials, the calculated $V_B^{\rm P}$ $(V_B^{\rm AP})$ values can differ substantially since, as mentioned before, in tunneling processes the bands along the transport direction, their symmetry character, and their matching across the interface play a decisive role. Indeed, the actual calculated $V_B^{\rm P}$ values in Fig. 6 are larger than the simple estimated ones for the parallel configuration, while for the anti-parallel configuration the calculated V_B^{AP} values are more close to the estimated ones. However, the simple estimated values set the lower limit of the breakdown voltages $V_B^{\rm P}$ and $V_B^{\rm AP}$.

Recently Maji and Nath reported the fabrication of a MTJ composed of HMM Co₂MnSi, SGS Ti₂CoSi, and 3 nm MgO tunnel barrier [56]. The authors demonstrated a reconfigurable diode effect with a relatively high on/off ratio of 10^3 and a very high TMR ratio of 892% at 5 K which decreases with increasing the temperature. Moreover, the breakdown voltage of the MTJ under reverse bias was reported to be around -0.5 V, which is basically the spin gap of the Co₂MnSi compound. Indeed, this is the first experimental demonstration of the concept that we proposed in 2019 [55]. Note that the authors in Ref. 56 used Ti₂CoSi as a SGS electrode, however, this material exhibits a type-III SGS behavior in simple DOS picture [64], whereas in tunneling experiments it behaves like a type-II SGS due to reasons that we discussed above. A detailed discussion of the experiments of Maji and Nath is beyond the scope of the present paper since we were aware of this work after the completion of

(a) (b) FeVTaAI/MgO/MnVTiAI FeVTiSi/MgO/CoFeVSb 100 100 75 75 50 50 TMR (%) 25 25 TMR (%) 0 0 -25 -25 3ML MgO 3ML MgO -50 -50 4ML MgO 4ML MgO 5ML MgO 5ML MgO -75 5ML MgO (SCF) -75 5ML MgO (SCF) 6ML MgO 6ML MgO • -100 -100-0.2 -0.1 0 0.1 02 0.3 -0.5 -0.4 -0.3 -0.2 -0.1 0 0.1 0.2 0.3 0.4 05 0.3 Voltage (V) Voltage (V)

FIG. 7. (a) Voltage dependence of the TMR ratio of the FeVTaAl/MgO/MnVTiAl MTJ for different MgO thicknesses calculated within the linear response approach. For the case of five monolayers of MgO thickness, the results are compared with SCF calculations. (b) The same as (a) of the FeVTiSi/MgO/CoFeVSb MTJ.

the present paper. However, we are planning to consider the MTJ of Ref. 56 in a separate future study.

The I-V characteristics discussed above as well as the TMR ratio, which will be discussed below, in our MTJs are calculated for zero temperature. The temperature effects (non-spin-flip thermal excitations, see Fig. 3) are usually included in NEGF transport calculations of semiconductor devices via the Fermi-Dirac distribution function. However, due to the technical limitation of the QUANTUMATK package as discussed in detail in Ref. 88 for spintronic materials, we neglected these thermal excitations in transport calculations. Moreover, besides high energy non-spin-flip thermal excitations, temperature affects the magnetic and electronic structure of the SGSs and HMMs via Stoner excitations and magnons or collective spin waves. In type-II SGSs, electrons around the Fermi energy can be excited via spin-flip with a nearly vanishing amount of energy [see Fig. 2(a)]. Such excitations are known as single-particle Stoner excitations and occupy, in our case, the unoccupied minority-spin states above E_F . As a consequence, these electrons contribute to a leakage current in the anti-parallel orientation of the magnetization direction of the type-II SGS and HMM electrode. On the other hand, due to the existence of a gap in HMMs. Stoner excitations are not allowed in these materials. Nevertheless, at finite temperatures, electronmagnon interactions might give rise to the appearance of non-quasiparticle sates in the spin gap above the Fermi level of HMMs [89]. As a consequence, these states reduce the spin-polarization of the HMM material and thus influence its transport properties. Furthermore, defects at the interface might also affect the characteristics of the SGSs and HMMs and contribute to a leakage current and reduce the on/off ratio and TMR effect.

Finally, we would like to discuss the TMR effect in the MTJs under study. As mentioned above, the reconfig-

urable diode effect gives rise to an inverse TMR effect in this type of MTJs. The voltage dependence of the TMR ratio for both MTJs is presented in Fig. 7(a) and 7(b)for four different MgO tunnel barrier thicknesses. Due to the computational efficiency, we stick here to the linear response approach, however, for five monolayers of MgO tunnel barrier thickness, we compare the obtained results with the SCF method. For negative bias voltages (reverse bias), both MTJs present a positive TMR effect while at a certain applied bias voltage, due to unique band structure of the SGS electrode, the TMR changes its sign to a negative value, and thus the MTJs exhibits an inverse TMR effect. In principle, for a perfect SGS electrode material, one expects a sharp transition from positive to negative TMR values at zero bias voltage as displayed in Fig. 1(a), however, in the present MTJs, this transition takes place in a finite voltage window and the transition point is shifted to finite voltages especially in the FeVTiSi/MgO/CoFeVSb tunnel junction. Two parameters are mainly responsible for the behavior of the TMR curves. These are the on/off current ratio, which reduces the TMR ratio, and the threshold voltage V_T , which causes a voltage shift of the transition point. Like in *I-V* curves, the spin gap of the electrode materials plays an essential role for the TMR ratio and its sign. For instance, in FeVTiSi/MgO/CoFeVSb tunnel junction the high TMR is obtained in a very small voltage window, especially for negative voltages and the TMR ratio is significantly reduced for voltages beyond the -0.3 V, which is more or less the spin gap of the HMM CoFeVSb material.

V. SUMMARY AND OUTLOOK

MTJs based on Fe, Co, and CoFeB, as well as HMM Heusler compounds, have been extensively studied in spintronics for magnetic memory and magnetic logic applications. Despite their high TMR ratios, especially the MTJs based on HMMs, conventional MTJs do not exhibit current rectification, i.e., a diode ef-A novel MTJ concept has been proposed in fect. Ref. 55, which exhibits reconfigurable current rectification together with an inverse TMR effect. This MTJ concept was based on HMMs and SGSs and it has been recently demonstrated experimentally using Heusler compounds [56]. In the present work, by employing the state-of-the-art DFT and NEGF methods, we designed two different MTJs based on the type-II SGS and HMM quaternary Heusler compounds FeVTaAl, We have shown FeVTiSi, MnVTiAl, and CoVTiSb. that both MTJs [FeVTaAl(001)/MgO/MnVTiAl(001) and FeVTiSi(001)/MgO/CoFeVSb(001)] exhibit a current rectification with a relatively high on/off ratio of up to 10^7 . We showed that in contrast to conventional semiconductor diodes such as p-n junction diode or Schottky diode, the rectification bias voltage window (or breakdown voltage) of these MTJs is limited by the spin gap of the HMM and SGS Heusler electrode material in agreement with recent experiments. A unique feature of the present MTJs is that they can be configured dynamically, i.e., depending on the relative orientation of the magnetization direction of the electrodes, the MTJ allows electrical current to pass either in one or the other direction. This feature gives rise to an inverse TMR effect in such devices. The inverse TMR effect has been investigated as a function of the MgO tunnel barrier thickness. We find that the sign change of the TMR from a positive to a negative value takes place not at zero bias voltage, but small finite voltages, which can be explained by the on/off ratio (leakage current) and threshold voltage V_T

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of the MTJs. Moreover, like in I-V curves, the spin gap of the electrode materials plays an essential role in TMR ratio and its sign.

The current non-volatile magnetic memory technology (STT-MRAM and beyond) and several magnetic logic proposals utilize conventional MTJs that have limited functionality. The MTJs based on HMMs and SGSs studied in the present paper provide major advantages over conventional MTJs and open new ways to magnetic memory and logic concepts. For instance, these MTJs might be of particular interest for high-density 3D cross-point STT-MRAM applications as they eliminate the need for an additional selection device such as a MOSFET transistor or a p-n diode. Apart from memory applications, the MTJs constitute the basic building blocks of the threeterminal magnetic tunnel transistors with unique properties as discussed in Ref. 55. Moreover, the present MTJs also open the way to logic-in-memory computing, i.e., storing and processing the data within the same chip and thus providing an opportunity to explore novel computing architectures beyond the classical von-Neumann architecture.

We expect that the present results will pave the way for experimentalists to fabricate MTJs based on the suggested Heusler compounds. Although in the present work we consider only a few materials, Heusler compounds represent a remarkable class of materials with more than 1000 members and offer a unique platform to grow within the same family of compounds HMMs and SGSs with similar lattice constants. Moreover, their HMM and SGS properties can be tuned by chemical doping and thus making them very promising for future spintronic devices with unique functionalities.

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Supplemental Material

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In the main text we discuss the current-voltage characteristics and tunnel magnetoresistance effect for the magnetic tunnel junctions (MTJs) based on quaternary Heusler compounds FeVTaAl, FeVTiSi, MnVTiAl, and CoVTiSb. In this supplementary part, we provide the zero-bias transmission spectrum for both MTJs (FeVTaAl/MgO/MnVTiAl and FeVTiSi/MgO/CoFeVSb) and device density of states (DDOS), as well as the transmission spectrum of the FeVTiSi/MgO/CoFeVSb junction in anti-parallel configuration at equilibrium (zero bias) and for an applied bias voltage of +0.2 V.



FIG. 1. Zero-bias transmission spectrum for majority spin and minority spin electrons in parallel (left panel) and anti-parallel (right panel) alignment of the magnetization direction of the (a) FeVTaAl/MgO/MnVTiAl and (b) FeVTiSi/MgO/CoFeVSb junction for 5 monolayers of MgO as tunnel barrier. The black dashed line displays the Fermi level which is set to 0.



FIG. 2. Projected device density of states (DDOS) for the majority (left panel) and minority (right panel) spin channel of the FeVTiSi/MgO/CoFeVSb junction for anti-parallel orientation of the magnetization directions of the electrodes (a) at equilibrium (zero bias) and (b) under an applied bias of voltage of +0.2 V. In the middle panels we present the transmission spectrum for both spin channels. The dashed lines displays the Fermi level of the left and right electrode while the vertical yellow dashed lines denote the interfaces between the electrodes and MgO. The MgO tunnel barrier thickness is taken to be 1.1 nm, i.e., five monolayers.